



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSB015N04NX3 G	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005699799		
<b>Package</b>	MG-WDSO-2-8	<b>Weight*</b>	86.37 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.356	7.36	7.36	73594	73594
leadframe	non noble metal	copper	7440-50-8	74.415	86.16	86.16	861570	861570
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.24		2445	
	noble metal	silver	7440-22-4	0.840	0.97	1.21	9725	12170
plating	non noble metal	nickel	7440-02-0	0.211	0.24	0.24	2445	2445
solder	non noble metal	copper	7440-50-8	0.011	0.01		127	
	noble metal	silver	7440-22-4	0.066	0.08		763	
	non noble metal	tin	7440-31-5	2.119	2.45	2.54	24528	25418
glue	miscellaneous	miscellaneous	-	0.031	0.04		357	
	plastics	acrylic resin	-	0.241	0.28		2795	
	noble metal	silver	7440-22-4	1.543	1.79	2.11	17861	21013
passivation	plastics	epoxy resin	-	0.327	0.38	0.38	3790	3790
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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